EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S177	5740	(438/14,18,108,763).CCLS.	USPAT; USOCR	OR	OFF	2011/09/26 01:10
S178	1104	S177 and (sputtering or ion adj milling)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/09/26 01:10
S179	250	S178 and (semiconductor and cleaning)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/09/26 01:10
S180	156	S179 and @ad< "20040225"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/09/26 01:10
S181	65	S180 and (argon or Ar or helium or He or neon or Ne)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/09/26 01:10
S182	5740	(438/14,18,108,763).CCLS.	USPAT; USOCR	OR	OFF	2011/09/26 01:11
S183	1104	S182 and (sputtering or ion adj milling)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/09/26 01:11
S184	250	S183 and (semiconductor and cleaning)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/09/26 01:11
S185	1916	(semiconductor with (wafer or substrate) with (test$3 or prob$3)) and ((ion milling) or (sputter$3 with etch$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/26 01:11
S186	1091	S185 and @ad< "20040225"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/09/26 01:11
S187	157	S186 and (((ion milling) or (sputter etch$3)) and (testing or probing or test or probe$1) with wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/26 01:11

EAST Search History (Interference)

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9/26/2011 2:41:03 AM
C:\Users\bau\Documents\EAST\Workspaces\Metallization\Electrical Contacts\10786807
bumps made of gold and its cleaning using ion milling before probing.wsp